

FEATURES:

- Phase-Lock Loop Clock Distribution for Applications ranging from 10MHz to 133MHz operating frequency
- Distributes one clock input to two banks of four outputs
- Separate output enable for each output bank
- External feedback (FBK) pin is used to synchronize the outputs to the clock input
- Output Skew <200 ps
- Low jitter <200 ps cycle-to-cycle
- 1/2x, 1x, 2x, 4x output options (see table):
 - IDT23S08T-1 1x
 - IDT23S08T-2 1x, 2x
 - IDT23S08T-3 2x, 4x
 - IDT23S08T-4 2x
 - IDT23S08T-5 1/2x
- No external RC network required
- Operates at 2.5V VDD
- Spread spectrum compatible
- Available in SOIC package

DESCRIPTION:

The IDT23S08T is a high-speed phase-lock loop (PLL) clock multiplier. It is designed to address high-speed clock distribution and multiplication applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 133MHz.

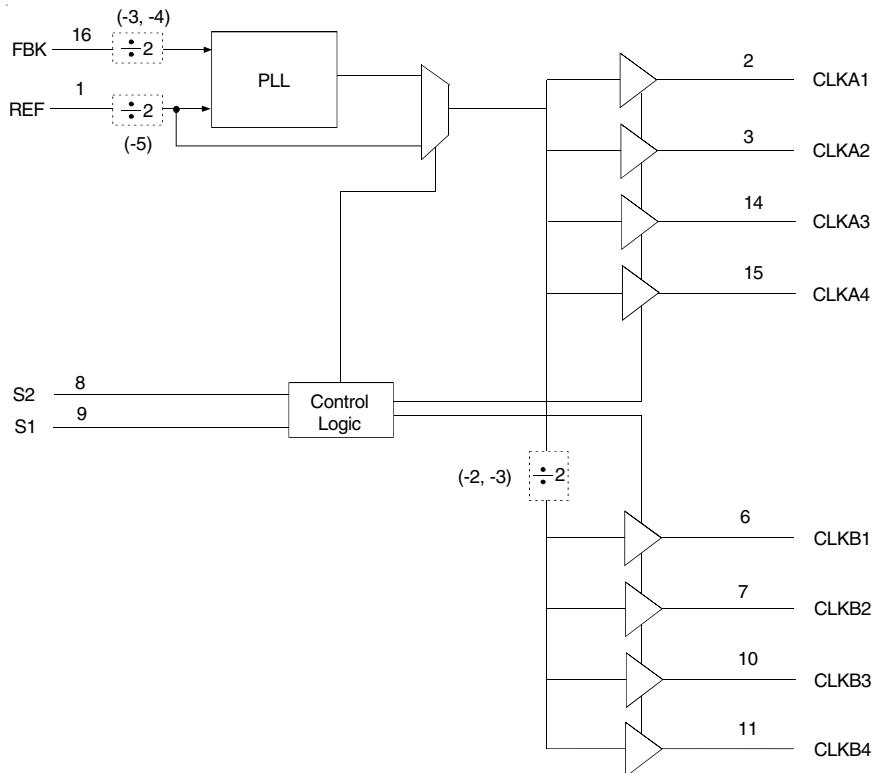
The IDT23S08T has two banks of four outputs each that are controlled via two select addresses. By proper selection of input addresses, both banks can be put in tri-state mode. In test mode, the PLL is turned off, and the input clock directly drives the outputs for system testing purposes. In the absence of an input clock, the IDT23S08T enters power down. In this mode, the device will draw less than 12 μ A, and the outputs are tri-stated.

The IDT23S08T is available in six unique configurations for both pre-scaling and multiplication of the Input REF Clock. (See available options table.)

The PLL is closed externally to provide more flexibility by allowing the user to control the delay between the input clock and the outputs.

The IDT23S08T is characterized for Commercial operation.

FUNCTIONAL BLOCK DIAGRAM

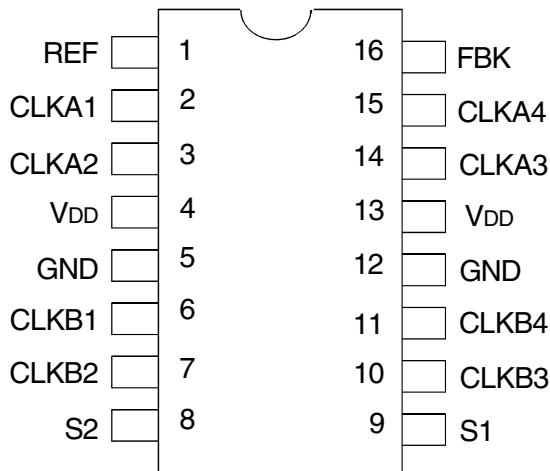


The IDT logo is a registered trademark of Integrated Device Technology, Inc.

COMMERCIAL TEMPERATURE RANGE

MARCH 2006

PIN CONFIGURATION



SOIC
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Max.	Unit
V _{DD}	Supply Voltage Range	-0.5 to +4.6	V
V _I ⁽²⁾	Input Voltage Range (REF)	-0.5 to +5.5	V
V _I	Input Voltage Range (except REF)	-0.5 to V _{DD} +0.5	V
I _{IK} (V _I < 0)	Input Clamp Current	-50	mA
I _O (V _O = 0 to V _{DD})	Continuous Output Current	±50	mA
V _{DD} or GND	Continuous Current	±100	mA
T _A = 55°C (in still air) ⁽³⁾	Maximum Power Dissipation	0.7	W
T _{STG}	Storage Temperature Range	-65 to +150	°C
Operating Temperature Range	Commercial Temperature Range	0 to +70	°C

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3. The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils.

PIN DESCRIPTION

	Pin Number	Functional Description
REF ⁽¹⁾	1	Input Reference Clock, 3.3V Tolerant Input
CLKA1 ⁽²⁾	2	Clock Output for Bank A
CLKA2 ⁽²⁾	3	Clock Output for Bank A
V _{DD}	4	2.5V Supply
GND	5	Ground
CLKB1 ⁽²⁾	6	Clock Output for Bank B
CLKB2 ⁽²⁾	7	Clock Output for Bank B
S2 ⁽³⁾	8	Select Input, Bit 2
S1 ⁽³⁾	9	Select Input, Bit 1
CLKB3 ⁽²⁾	10	Clock Output for Bank B
CLKB4 ⁽²⁾	11	Clock Output for Bank B
GND	12	Ground
V _{DD}	13	2.5V Supply
CLKA3 ⁽²⁾	14	Clock Output for Bank A
CLKA4 ⁽²⁾	15	Clock Output for Bank A
FBK	16	PLL Feedback Input

NOTES:

1. Weak pull down.
2. Weak pull down on all outputs.
3. Weak pull ups on these inputs.

APPLICATIONS:

- SDRAM
- Telecom
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs

FUNCTION TABLE⁽¹⁾ SELECT INPUT DECODING

S2	S1	CLK A	CLK B	Output Source	PLL Shut Down
L	L	Tri-State	Tri-State	PLL	Y
L	H	Driven	Tri-State	PLL	N
H	L	Driven	Driven	REF	Y
H	H	Driven	Driven	PLL	N

NOTE:

1. H = HIGH Voltage Level
- L = LOW Voltage Level

AVAILABLE OPTIONS FOR IDT23S08T

Device	Feedback From	Bank A Frequency	Bank B Frequency
IDT23S08T-1	Bank A or Bank B	Reference	Reference
IDT23S08T-2 ⁽¹⁾	Bank A	Reference	Reference/2
IDT23S08T-2 ⁽¹⁾	Bank B	2 x Reference	Reference
IDT23S08T-3 ⁽¹⁾	Bank A	2 x Reference	Reference or Reference ⁽²⁾
IDT23S08T-3 ⁽¹⁾	Bank B	4 x Reference	2 x Reference
IDT23S08T-4 ⁽¹⁾	Bank A or Bank B	2 x Reference	2 x Reference
IDT23S08T-5 ⁽¹⁾	Bank A or Bank B	Reference/2	Reference/2

NOTES:

1. Contact factory for availability.
2. Output phase is indeterminant (0° or 180° from input clock).

SPREAD SPECTRUM COMPATIBLE

Many systems being designed now use a technology called Spread Spectrum Frequency Timing Generation. This product is designed not to filter off the Spread Spectrum feature of the reference input, assuming it exists. When a zero delay buffer is not designed to pass the Spread Spectrum feature through, the result is a significant amount of tracking skew, which may cause problems in systems requiring synchronization.

ZERO DELAY AND SKEW CONTROL

To close the feedback loop of the IDT23S08T, the FBK pin can be driven from any of the eight available output pins. The output driving the FBK pin will be driving a total load of 7pF plus any additional load that it drives. The relative loading of this output (with respect to the remaining outputs) can adjust the input-output delay.

For applications requiring zero input-output delay, all outputs including the one providing feedback should be equally loaded. Ensure the outputs are loaded equally, for zero output-output skew.

OPERATING CONDITIONS

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V _{DD}	Supply Voltage		2.3	2.7	V
T _A	Operating Temperature (Ambient Temperature)		0	70	°C
C _L	Load Capacitance from 10MHz to 133MHz		—	15	pF
C _{IN}	Input Capacitance ⁽¹⁾		—	7	pF

NOTE:

1. Applies to both REF and FBK.

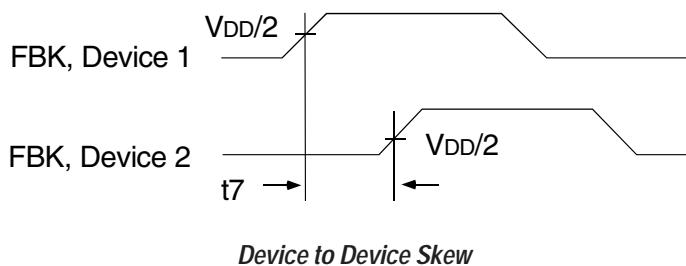
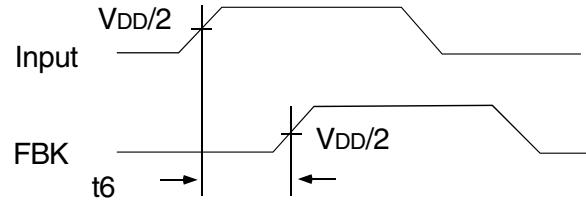
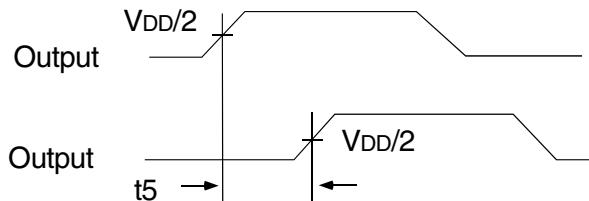
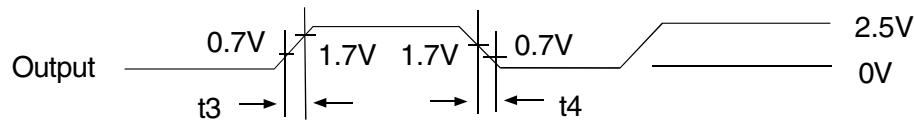
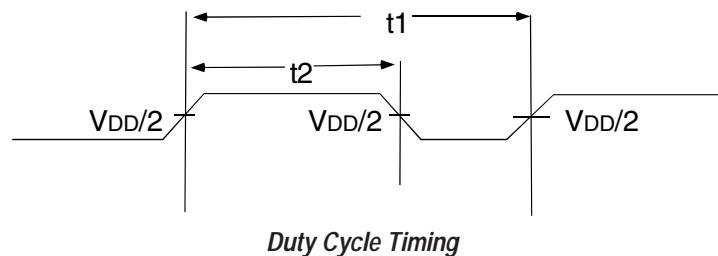
DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
V _{IL}	Input LOW Voltage Level		—	—	0.7	V
V _{IH}	Input HIGH Voltage Level		1.7	—	—	V
I _{IL}	Input LOW Current	V _{IN} = 0V	—	—	50	µA
I _{IH}	Input HIGH Current	V _{IN} = V _{DD}	—	—	100	µA
V _{OL}	Output LOW Voltage	I _{OL} = 8mA	—	—	0.3	V
V _{OH}	Output HIGH Voltage	I _{OH} = -8mA	2	—	—	V
I _{DD_PD}	Power Down Current	REF = 0MHz (S2 = S1 = H)	—	—	12	µA
I _{DD}	Supply Current	Unloaded Outputs Select Inputs at V _{DD} or GND	100MHz CLKA	—	—	45
			66MHz CLKA	—	—	32
			33MHz CLKA	—	—	18

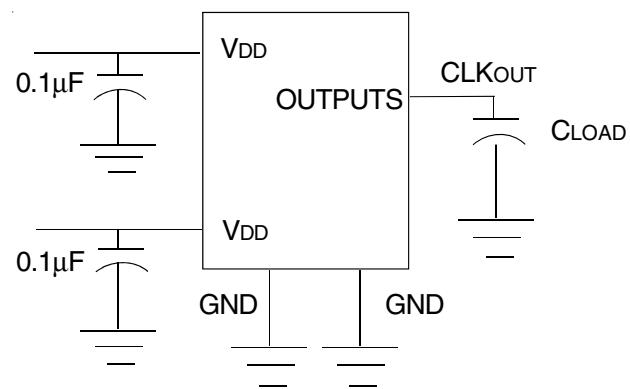
SWITCHING CHARACTERISTICS

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t ₁	Output Frequency	15pF Load	10	—	133.3	MHz
	Duty Cycle = t ₂ ÷ t ₁	Measured at V _{DD} /2, F _{OUT} = 66.66MHz, 15pF Load	40	50	60	%
t ₃	Rise Time	Measured between 0.7V and 1.7V, 15pF Load	—	—	2.5	ns
t ₄	Fall Time	Measured between 0.7V and 1.7V, 15pF Load	—	—	2.5	ns
t ₅	Output to Output Skew on same Bank (-1, -2, -3, -4, -5)	All outputs equally loaded	—	—	200	ps
	Output Bank A to Output Bank B (-1, -4, -5)	All outputs equally loaded	—	—	200	ps
	Output Bank A to Output Bank B Skew (-2, -3)	All outputs equally loaded	—	—	400	ps
t ₆	Delay, REF Rising Edge to FBK Rising Edge	Measured at V _{DD} /2	—	0	±350	ps
t ₇	Device to Device Skew	Measured at V _{DD} /2 on the FBK pins of devices	—	0	700	ps
t ₈	Cycle to Cycle Jitter (-1, -4, -5)	Measured at 66.67 MHz, loaded outputs, 15pF Load	—	—	200	ps
		Measured at 133.3 MHz, loaded outputs, 15pF Load	—	—	200	ps
t ₉	Cycle to Cycle Jitter (-2, -3)	Measured at 66.67 MHz, loaded outputs, 15pF Load	—	—	400	ps
t _{LOCK}	PLL Lock Time	Stable Power Supply, valid clocks presented on REF and FBK pins	—	—	1	ms

SWITCHING WAVEFORMS



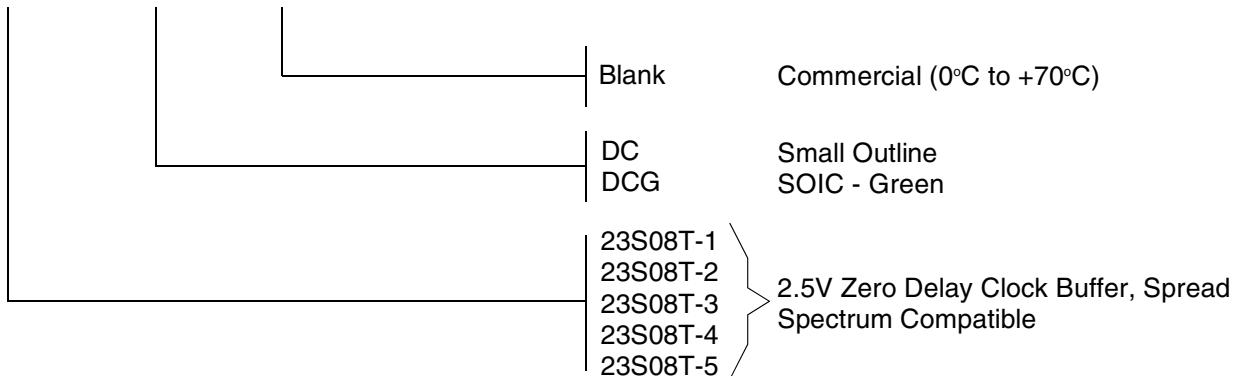
TEST CIRCUIT



Test Circuit for all Parameters

ORDERING INFORMATION

IDT XXXXX XX X
Device Type Package Process



IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers who are designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only to develop an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third-party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising from your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.01)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit www.renesas.com/contact-us/.